

Docket: APS03-003

S/N: 10/742,306

To: Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

From: Stephen B. Ackerman, Reg. No. 37,761
Saile Ackerman LLC
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No.: 10/742,306	Filed: 12/19/2003
First Named Inventor: Chng Han Shen	
Title: Various Structure/Height Bumps For Wafer Level-Chip Scale Package	
Group Art Unit: 2811	Examiner: Im, Junghwa M.
Attorney Docket: APS03-003	

RESPONSE TO PATENT OFFICE ACTION

Dear Sir:

In response to the Final office action dated 07/26/2006, please consider the following remarks:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on September 26, 2006.

Signature/Date



9/26/06

Stephen B. Ackerman
Reg. No. 37,761

Charge to Deposit Account

The Commissioner is hereby authorized to charge payment of the fee of \$_____ associated with this communication, or credit any overpayment, to Deposit Account No. 19-0033. The Commissioner is also authorized to charge any additional fee under 37 CFR §1.16 and 1.17 to this Deposit Account. A duplicate copy of this sheet is enclosed. The Commissioner is hereby authorized to charge payment of any additional fees involved with added Claims and the like to Deposit Account No. 19-0033.

Respectively submitted,

9/26/06

Date



Stephen B. Ackerman; or
George O. Saile

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The Amendments to the Claims begin on page 4 and the Remarks
begin on page 13.